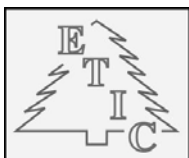


Notes:

1. Package body sizes excludes mold flash protrusions and gate bars.
2. Tolerance $\pm 0.1\text{mm}$ unless otherwise specified.
3. Coplanarity: 0.1mm
4. Controlling dimension is millimeter, and converted inches may not be exact.
5. Die pad exposure size is according to lead frame design. Protrusion of pad below mold body is 0.05mm maximum.
6. Refer to JEDEC MO-153.

| SYMBOLS | DIMENSIONS IN MILLIMETER | | | DIMENSIONS IN INCH | | |
|----------|--------------------------|------|------|--------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | --- | --- | 1.15 | --- | --- | 0.045 |
| A1 | 0.00 | --- | 0.10 | 0.000 | --- | 0.004 |
| A2 | 0.80 | 1.00 | 1.05 | 0.031 | 0.039 | 0.041 |
| b | 0.19 | --- | 0.30 | 0.007 | --- | 0.012 |
| C | 0.09 | --- | 0.20 | 0.004 | --- | 0.008 |
| D | 7.70 | 7.80 | 7.90 | 0.303 | 0.307 | 0.311 |
| E | 6.20 | 6.40 | 6.60 | 0.244 | 0.252 | 0.260 |
| E1 | 4.30 | 4.40 | 4.50 | 0.169 | 0.173 | 0.177 |
| e | --- | 0.65 | --- | --- | 0.026 | --- |
| L | 0.45 | 0.60 | 0.75 | 0.018 | 0.024 | 0.030 |
| y | --- | --- | 0.10 | --- | --- | 0.004 |
| θ | 0° | --- | 8° | 0° | --- | 8° |
| L1-L1' | --- | --- | 0.12 | --- | --- | 0.005 |
| L1 | 1.00REF | | | 0.039REF | | |



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Title: **Package Drawing for 24 lead TSSOP (exposed pad)**
 Dwg: **12-0005-001** Rev: **B**